

# KIMOTECT™

## 用于感光性阻焊剂的保护膜

For Liquid Solder Resist

**PA8X**

基材厚度 Base Film Thickness	粘着层厚度 Adhesive Thickness	离型纸厚度 Release Liner Thickness
6 μm	2 μm	25 μm

感光性阻焊剂不易粘附，容易清洁，  
不残胶，可以再剥离。

PA8X是感光性阻焊剂用保护膜的标准型号。

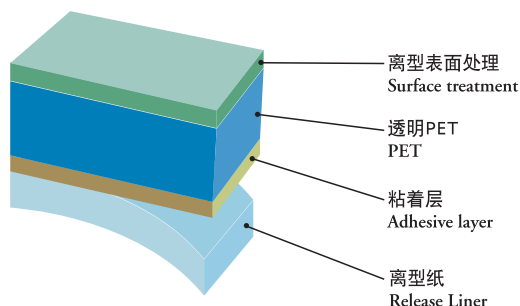
PA8X can be easily removed from the surface of the phototools and is peelable without any remnants of adhesive.  
PA8X is a standard type for the Liquid Solder Photo Resist Series.

**PA8XM**

基材厚度 Base Film Thickness	粘着层厚度 Adhesive Thickness	离型纸厚度 Release Liner Thickness
6 μm	2 μm	25 μm

因采用含砂剂进行表面处理，使得密着性和真空度得以提高。

A matted surface improves adhesion and vacuum pressure.



特性 Properties

	PA8X	PA8XM
全光线透率 (%) *1 Total Light Transmittance	92.9	92.2
平行光透率 (%) *1 Parallel Light Transmittance	90.8	85.6
紫外线透率 *2 (% / 365nm) UV Light Transmittance	87.9	89.5
紫外线透率 *2 (% / 420nm) UV Light Transmittance	87.4	90.0
Haze(%)*1	2.1	7.2
粘着力 (对PET) Adhesive Force for PET	2.5N/25mm	2.6N/25mm

\*1: 根据JIS-K7105规格标准测定。离型纸不包含在内。

\*2: 使用岛津制作所公司制造的UV-3101PC测定。离型纸不包含在内。

\*1: JIS-K7105 without Release Film. \*2: Simazu UV-3101PC without Release Liner.